

Date: 03/27/20

Attendees: Dan, Eelco, Jawad, Kevin, Manoj, Mark, Paul, Scott, Ali, Sean, DJ, Reza, Rita, Jia, Manuel, Tawfik, Sam, David, Jinshui, Bapi, JP

Agenda:

1. ODSA Session at Virtual Summit (panels, short sessions)
 2. Eelco - ASE
 3. Jia Ning - FB - Modularity Initiative
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1. Modularization Task Group (Jia)
 - a. Kicking off an effort inside OCP, inviting participation
 - b. Jia Ning, John Stuewe, Siamak Tavellei for questions
 - c. Is there a roadmap for deliverables, none yet in scoping stage
 - d. DJ - aim to disseminate modules to new applications e.g. ODSA using OCP NIC3.0 as a form factor, gather requirements across groups to module owners
 2. ASE (notes thanks to Jawad)
 - a. Eelco gave a talk about the packaging perspective and ASE's interest in ODSA.
 - b. -Background of ASE includes assembly and test and more of system integration (USI) which is a growing business.
 - c. -Now that Moores law is slowing, advance packaging is where the renewed innovations are.
 - d. -IC Packaging bridges the gap in Si and PCB in terms of the technology.
 - e. -Die disaggregation and partitioning has been happening in more recent IC technologies for cost and performance reasons.
 - f. -Eelco explained packaging processes for SIP/MCM, 2.5DTSV, and FOCoS.
 - g. -FOCoS cost can be lower than the silicon interposer based solutions for HBM.
 - h. -Yields of FOCoS are comparable to CoWoS.
 - i. -Call to Action: Virtual prototyping of PoC for packaging using BoW footprint standardization in the CDX group. More details to follow at a late date.
 3. OCP Agenda
 - a. Short talks -
 - b. Panels
 - i. Rita prefers Friday option
 - ii. Manuel
 - c. We're going to aim for live audiences - Friday 4/3 and 4/10 if the schedule works for the virtual summit organizers.